

TSMC RUN SCHEDULE 2027

October, 2026 – v1.0

MINI@SIC RUN SCHEDULE 2027



Technology	Month	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS*	Tape-out	Estimated shipment date
16nm RF FinFET Compact (0.8/1.8V)	February	I0212	TM0C80	14	Oct 26 2026	Dec 22 2026	Jan 12	Feb 09	Feb 22	May 22-Jun 28
	August	I0213	TM0C83	14	Apr 28	Jul 1	Jul 20	Aug 17	Aug 30	Nov 27-Dec 31
22 nm CMOS RF ULL (0.8/2.5V)	July	I0220	TM0CA5	15	Mar 25	May 14	Jun 2	June 30	Jul 13	Oct 7-Nov 10

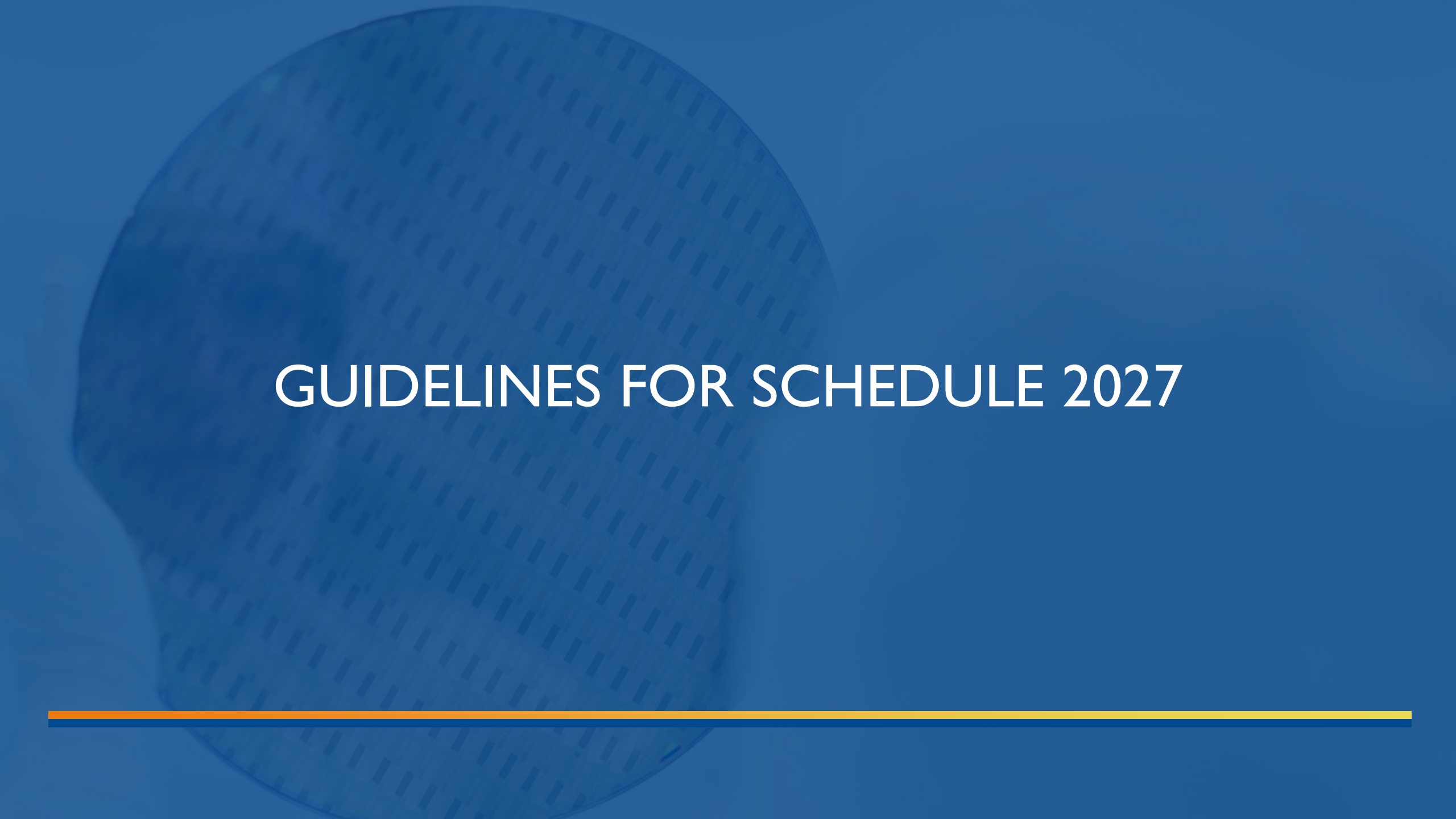
*Provide final GDS two weeks earlier in case of IP merge. In case of LVS or other services are required, please reach out to eptsmc@imec.be at the purchase order stage.

Mini@sic RUN SCHEDULE 2027 – 28nm-65nm

Technology	Month	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS*	Tape-out	Estimated shipment date
28nm CMOS RF HPC Plus ELK Cu 0.9/1.8V [RF HPC +]	February	I0228	TM0CB1	15	Oct 26 (2026)	Dec 22 (2026)	Jan 13	Feb 10	Feb 23	May 13-Jun 17
	May	I0229	TM0CB3	15	Jan 27	Mar 19	Apr 07	May 05	May 18	Aug 05- Sep 09
	August	I0230	TM0CB5	15	Apr 28	Jun 18	Jul 07	Aug 04	Aug 17	Nov 04-Dec 09
	November	I0231	TM0CB7	15	Jul 27	Sep 17	Oct 06	Nov 03	Nov 16	Feb 03-Mar 09 (2028)
65 nm CMOS Mixed Signal RF Low Power Standard Process LowK Cu 1.2&2.5V	January	I0245	TM0CD1	14	Oct 05	Nov 06	Nov 17 2026	Dec 15 2026	Jan 05	Mar 16-Apr 20
	March	I0246	TM0CD2	12	Nov 25	Jan 02	Jan 20	Feb 17	Mar 02	May 11-Jun 15
	April	I0247	TM0CD3	14	Dec 28 (2026)	Feb 19	Mar 10	Apr 07	Apr 20	Jun 29-Aug 03
	July	I0248	TM0CD5	12	Mar 25	May 14	Jun 02	Jun 30	Jul 13	Sep 21-Oct 26
	September	I0249	TM0CD6	14	May 25	Jul 09	Jul 28	Aug 25	Sep 07	Nov 16-Dec 21
	November	I0250	TM0CD7	12	Jul 27	Sep 3	Sep 22	Oct 20	Nov 2	Jan 11-Feb 15 (2028)

* Provide final GDS two weeks earlier in case of IP merge. In case of LVS or other services are required, please reach out to eptsmc@imec.be at the purchase order stage.

GUIDELINES FOR SCHEDULE 2027



- Single reservation for multiple chips
- No backup reservation
- Provide single GDS with all designs,
 - ▶ Enclosed with TSMC searing + 80um scribe (post-shrink if applicable).
 - ▶ If designs are not identical, put marker in the scribe line.
 - ▶ Add dummies to the scribe line for 12-inch tape-outs.
 - ▶ Exception: multiple reservations accepted for different projects with different metal stacks or far backend.

- The estimated shipment date is applicable for reservations with quantity <200 dies.
- If additional samples are required, additional cycle time of (1~3 weeks) might be needed.
- Cycle time estimates are based on typical conditions. Corner wafers or SHDMiM processing requires additional cycle time.
- Optional services adding cycle time
 - ▶ Wafer thinning (thinner than 10mils): up to 12 days
 - ▶ Additional bumped wafer thinning and die saw (each 200 ea.): 5 -21 working days

- To ensure timely inclusion in the TSMC MPW when an IP merge is required, deliver the final GDS 2 weeks in advance to allow sufficient time for integration and validation.
- Why This Matters:
 - ▶ **Complete LVS Setup Required**
A fully validated LVS setup must be in place before initiating the merge process.
 - ▶ **Ip-transfer**
Third-party IPs have to be transferred from the vendor to the TSMC merge team, which may introduce delays in the process.
 - ▶ **Increased Complexity with Multiple IP Instances**
Merging several IP blocks adds significant complexity and increases the risk of integration issues.
 - ▶ **Merge Errors Can Jeopardize the Deadline**
Errors discovered after merging may delay the process and reduce the likelihood of meeting the MPW schedule. TSMC requests to re-submit the merge even for minor typos or missing files

Contact our teams through a portal support case:

Support Tape-out	For support on the tape-out submission
Support SalesOps	For support on portal, quotations, export documents, purchase orders, and design registration questions
Support EP packaging	For any question related to the Europractice packaging offer.
Support Foundry	For support on foundry libraries, PDK's (installation, flavors, bugs, ...), LVS

- October 2026
 - ▶ Release of v1.0 2026



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